

**RHEM PROCESSES**

**Ø Copper**

- § PCM ADDITIVE AND CARRIER
- § PCM+ ADDITIVE AND CARRIER
- § 125 T2 ADDITIVE
- § 125 T-AB PART A AND B
- § 2001 ADDITIVE AND CARRIER
- § PPR ADDITIVE AND CARRIER
- § PPR-H CARRIER
- § PPR TW ADDITIVE
- § ST 901 ADDITIVE AND CARRIER
- § EP 1100 ADDITIVE AND CARRIER
- § EP 1200 ADDITIVE AND CARRIER
- § VIAFILL ADDITIVE
- § MICRO FILL
- § CUPULSE – TBA

**Ø Tin / Tin Lead**

- § SOLDERON SC PRIMARY
- § SOLDERON PC
- § SOLDERON LG
- § ST 200
- § ST 300
- § ST 380
- § EC
- § BT 100

**ATOTECH PROCESSES**

**Ø Copper**

- § BLCT BRIGHTENER AND LEVELLER
- § CUPRAPULSE S3-S4 BRIGHTENER AND LEVELLER
- § UP BRIGHTENER AND LEVELLER
- § INPULSE BRIGHTENER AND LEVELLER
- § INPLATE BRIGHTENER AND LEVELLER

**ENTHONE PROCESSES**

- Ø Copper
  - § CUPROSTAR ST 2000 BST AND CST
  - § CUBATH SC MD AND LO ADDITIVE
- Ø Tin / Tin Lead
  - § STANNOSTAR GMB

**TECHNIC PROCESSES**

- Ø Copper
  - § Cu 2300 BRIGHTENER AND CARRIER
- Ø Tin / Tin Lead
  - § NB 93

**SCHLÖTTER PROCESSES**

- Ø Copper
  - § SLOTOCUP CU 50
- Ø Tin / Tin Lead
  - § KB 51
  - § SLOTOTIN 30
  - § SLOTOTIN 41

**ELECTROCHEMICALS PROCESSES**

- Ø Copper
  - § PC 667 ADDITIVE
  - § PC 671 ADDITIVE

**UYEMURA PROCESS**

- Ø Copper
  - § EVF

**AEM PROCESSES**

- Ø Tin / Tin Lead
  - § PRIMARY 1104
  - § 1124 ADDITIVE

**COVENTYA PROCESSES**

- Ø Tin / Tin Lead
  - § STABAC 501

